

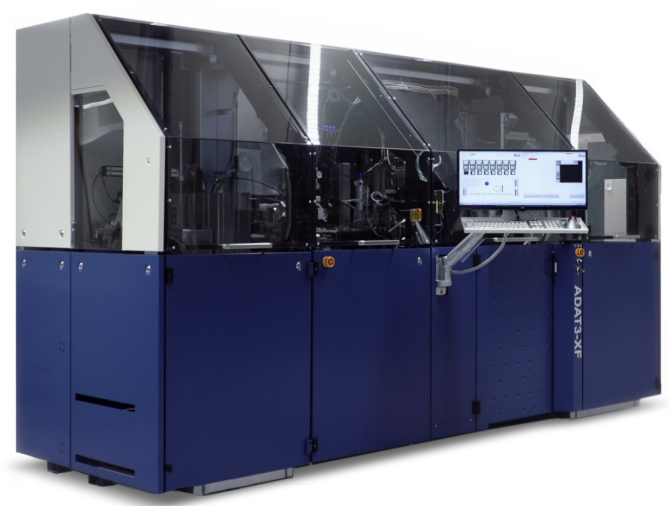
ADAT3XF DBSG Die Bonder Strip Glue

Application

- High Speed Strip to Strip Diebonder
- QFN, HVQFN, SOT, SO, TSSOP, LGA

Key Feature

- up to 60000 UPH
- Support 8" 12" wafer on Frame Film Carrier
- 100 x 300 mm stripsize
- Glue/DAF/WBC
- Min Die size 0.2 x 0.2 mm
- Max Die size 5 x 5 mm
- Automatic wafer change and expander
- High throughput at high-volume manufacturing rate
- 4 cassettes at input outloader
- 4 cassettes at input (option)
- Full die traceability (strip E142 - wafer)
- Auto recipe download (MES interface)
- SECS/GEM interface with E142



System accuracy

Small die (<1mm)	
XY	1 σ xy \leq 5 μ m
Rotation	1 σ ϕ < 1°
Large die (>1mm)	
XY	1 σ xy \leq 5 μ m
Rotation	1 σ ϕ < 0.3°

Inspection Categories

Program Mode:	Fast programming for common reject criteria		
Reject treatment:	Stripmap (E142) and reject bin		
Inspection View:	4 cam: (1) glue (2) pre pick (3) back (4) Postbond		
Inspection items:	Die related: - top Chipping , backside Chipping - Damaged - Die size/Die ratio - Scratch - Cracked die - Discoloration	Glue related: - Dropsizes - dropshape	Postbond related: - Die alignment (position, size, and rotation) - Glue fillet

Imaging System

Camera	
Number of camera	4
Resolution / FOV GLUE	0.3Mp camera (3.2µm/pixel), FOV 2.1 x 1.x4 mm
Resolution / FOV PICK UP & BACKSIDE	5.0Mp camera (2.3µm/pixel), FOV 5.6 x 4.7 mm
Resolution / FOV Post BOND	5.0Mp camera (4.6µm/pixel), FOV 11.3 x 9.4 mm
Resolution / FOV SIDEWALL	(option)
Resolution / FOV Die ON FLIP	NA
Resolution / FOV POST SEAL INSPECTION	NA
POSTSEAL INSPECTION	NA
Min object detection	10µm
Lighting	Coaxial & ringlight including multicolor light

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